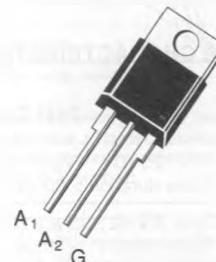


SNUBBERLESS TRIACS

- $I_{TRMS} = 16 \text{ A}$ at $T_c = 80^\circ\text{C}$.
- $V_{DRM} : 200 \text{ V}$ to 800 V .
- $I_{GT} = 35 \text{ mA}$ (QI-II-III).
- GLASS PASSIVATED CHIP.
- HIGH SURGE CURRENT : $I_{TSM} = 150 \text{ A}$.
- HIGH COMMUTATION CAPABILITY :
 $(di/dt)_c > 8.5 \text{ A/ms}$ without snubber.
- INSULATING VOLTAGE : 2500 VRMS .
- UL RECOGNIZED (E81734).

DESCRIPTION

New range suited for applications such as phase control and static switching on inductive or resistive load.


TO 220 AB
 (CB-415 Plastic)

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
I_{TRMS}	RMS on-state current (360 ° conduction angle)	16	A
I_{TSM}	Non repetitive surge peak on-state current (T_j initial = 25°C)	$t = 8.3 \text{ ms}$	157
		$t = 10 \text{ ms}$	150
I^2t	I^2t value	112	A^2s
di/dt	Critical rate of rise of on-state current (1)	Repetitive $F = 50 \text{ Hz}$	20
		Non Repetitive	$\text{A}/\mu\text{s}$
T_{stg} T_i	Storage and operating junction temperature range	- 40, + 150 - 40, + 125	$^\circ\text{C}$

Symbol	Parameter	BTA 16-					Unit
		200 CW	400 CW	600 CW	700 CW	800 CW	
V_{DRM}	Repetitive peak off-state voltage (2)	± 200	± 400	± 600	± 700	± 800	V

(1) Gate supply : $I_G = 350 \text{ mA} - di_G / dt = 1 \text{ A}/\mu\text{s}$.

(2) $T_j = 125^\circ\text{C}$.

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th\ (j-a)}$	Junction to ambient	60	°C/W
$R_{th\ (j-c)\ DC}$	Junction to case for DC	3.1	°C/W
$R_{th\ (j-c)\ AC}$	Junction to case for 360 ° conduction angle ($F = 50$ Hz)	2.3	°C/W

GATE CHARACTERISTICS (maximum values)

$P_{GM} = 40$ W ($t = 10$ µs) $P_{G(AV)} = 1$ W $I_{GM} = 4$ A ($t = 10$ µs) $V_{GM} = 16$ V ($t = 10$ µs).

ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions		Quadrants	Min.	Typ.	Max.	Unit
I_{GT}	$T_j = 25$ °C	$V_D = 12$ V	$R_L = 33 \Omega$	I-II-III	1	35	mA
	Pulse duration > 20 µs					1.5	V
V_{GT}	$T_j = 25$ °C	$V_D = 12$ V	$R_L = 33 \Omega$	I-II-III			
	Pulse duration > 20 µs						
V_{GD}	$T_j = 125$ °C	$V_D = V_{DRM}$	$R_L = 3.3$ kΩ	I-II-III	0.2		V
	Pulse duration > 20 µs						
I_H *	$T_j = 25$ °C Gate open	$I_T = 100$ mA $R_L = 140 \Omega$				35	mA
I_L	$T_j = 25$ °C	$V_D = 12$ V	$I_G = 350$ mA	I-III		50	mA
	Pulse duration > 20 µs			II		80	
V_{TM} *	$T_j = 25$ °C	$I_{TM} = 22.5$ A	$t_p = 10$ ms			1.5	V
I_{DRM} *	$T_j = 25$ °C $T_j = 125$ °C	V_{DRM} rated	Gate open			0.01	mA
						2	
dv/dt *	$T_j = 125$ °C Gate open	Linear slope up to 0.67 V_{DRM}			250	500	V/µs
$(di/dt)_c$ *	$T_j = 125$ °C	V_{DRM} rated Without snubber			8.5	17	A/ms
t_{gI}	$T_j = 25$ °C $I_T = 22.5$ A	$di_G/dt = 1$ A/µs $V_D = V_{DRM}$	$I_G = 350$ mA	I-II-III		2	µs

* For either polarity of electrode A₂ voltage with reference to electrode A₁.

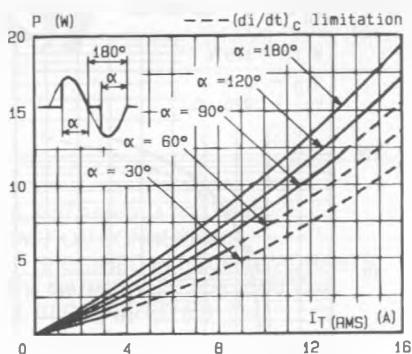


Fig.1 - Maximum mean power dissipation versus RMS on-state current ($F = 60$ Hz).

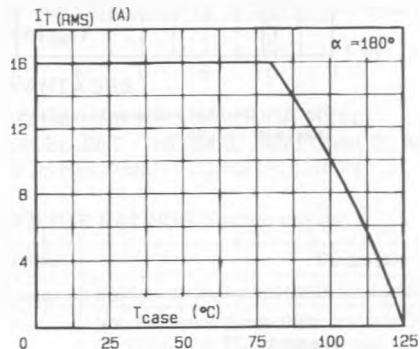


Fig.3 - RMS on-state current versus case temperature.

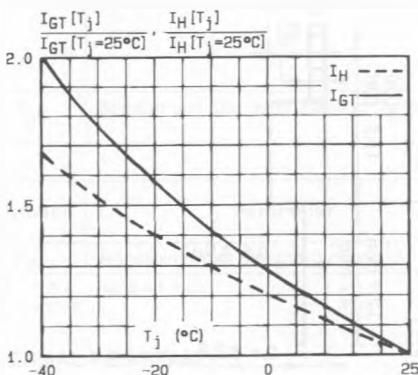


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

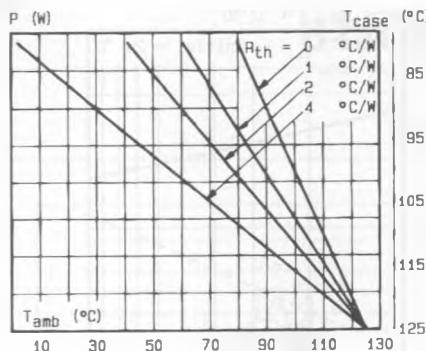


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

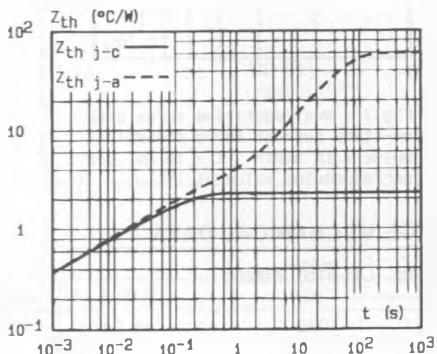


Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

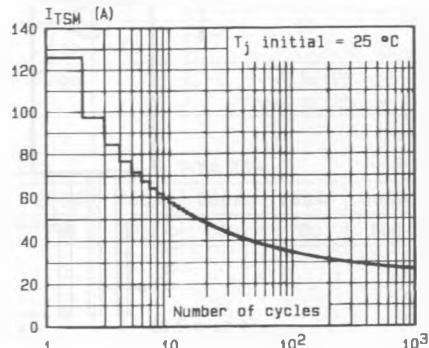


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.

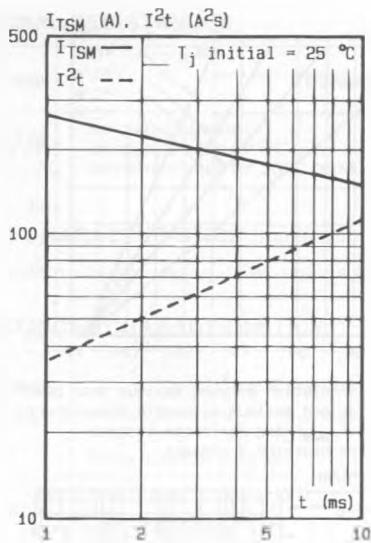


Fig.7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms, and corresponding value of I^2t .

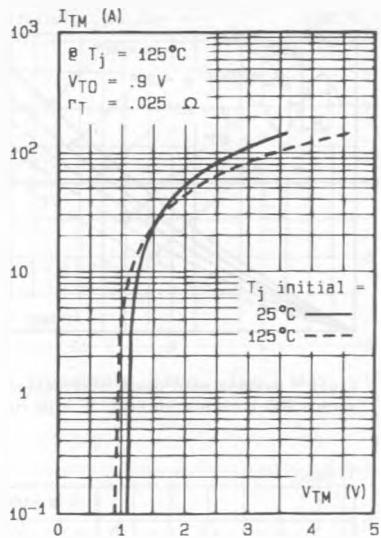
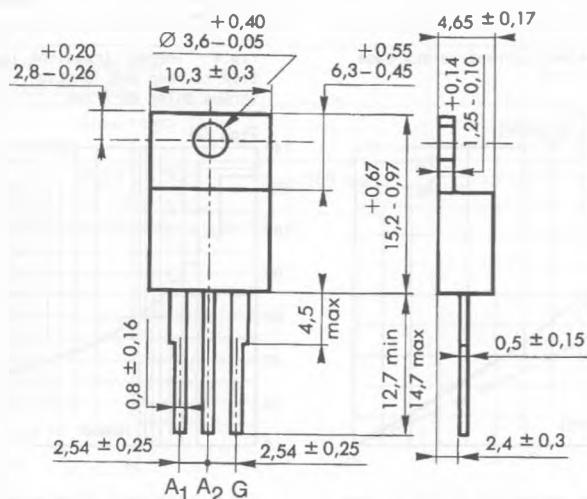


Fig.8 - On-state characteristics (maximum values).

PACKAGE MECHANICAL DATA

TO 220 AB (CB-415) Plastic



Cooling method : by conduction (method C)

Marking : type number

Weight : 2 g